

AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application:

LISTING OF CLAIMS:

Claims 1-7 (canceled).

Claim 8 (previously presented): A method of producing a piezoelectric component according to Claim 20, wherein in the sealing step, the step of hot-press bonding step is repeated, and thereafter, a step of pressing the resin film from the upper side thereof is carried out by a mold-frame.

Claims 9-19 (canceled).

Claim 20 (previously presented): A method of producing a piezoelectric component comprising the steps of:

forming a plurality of piezoelectric elements having a vibrating portion and a bump on a substrate;

mounting the plurality piezoelectric elements on a mounting substrate having external terminals via the bumps by flip chip bonding such that the vibrating portions are opposed to the mounting substrate;

arranging a resin film on the mounting substrate having the plurality of piezoelectric elements mounted thereon;

sealing the plurality of piezoelectric elements by embedding the resin film between adjacent ones of the piezoelectric elements mounted on the mounting substrate;

hardening the resin film; and

splitting the mounting substrate by dicing to form individual piezoelectric components; wherein

the sealing step includes a step of hot-press bonding in which the resin film is heated, softened, and simultaneously pressed by a roller;

in the step of hot-press bonding, the mounting substrate having the piezoelectric elements mounted thereon is fixed to a flat-surface stage for the step of hot-press bonding; and

a height d of the piezoelectric component, a volume V of one of the plurality of piezoelectric elements including the bumps and the gap between the piezoelectric element and the mounting substrate, a number n of piezoelectric elements per unit area on the mounting substrate, a thickness t_1 of the resin film, and an average thickness t_2 of the mounting substrate (cross-sectional area/length of substrate) have a relationship expressed by $0.8 < d/(nV + t_1 + t_2) < 1.1$.

Claims 21-38 (canceled)

Claim 39 (previously presented): A method of producing a piezoelectric component comprising the steps of:

forming a plurality of piezoelectric elements each having a vibrating portion and a bump on a substrate;

mounting the plurality piezoelectric elements on a mounting substrate having external terminals via the bumps by flip chip bonding such that the vibrating portions are opposed to the mounting substrate;

arranging a resin film on the mounting substrate having the plurality of piezoelectric elements mounted thereon;

sealing the plurality of piezoelectric elements by embedding the resin film between adjacent ones of the piezoelectric elements mounted on the mounting substrate;

hardening the resin film; and

splitting the mounting substrate by dicing to form individual piezoelectric components; wherein

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the sealing step includes a step of hot-press bonding in which the resin film is heated, softened, and simultaneously pressed by a roller; and

a height d of one of the plurality of piezoelectric components, a volume V of said one of the plurality of piezoelectric elements including the bumps and the gap between said one of the plurality of piezoelectric elements and the mounting substrate, a number n of piezoelectric elements per unit area on the mounting substrate, a thickness t_1 of the resin film, and an average thickness t_2 of the mounting substrate (cross-sectional area/length of substrate) have a relationship expressed by $0.8 < d/(nV + t_1 + t_2) < 1.1$.